



SOT1688-2(SC)

HLQFN16; plastic, thermal enhanced low profile quad flat non-leaded package; 16 terminals; 0.8 mm pitch; 4 mm x 4 mm x 1.37 mm body

29 May 2019

Package information

1 Package summary

Terminal position code	Q (quad)
Package type descriptive code	HLQFN16
Package type industry code	HLQFN16
Package style descriptive code	HLQFN (thermal enhanced low profile quad flatpack; no leads)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	09-05-2019
Manufacturer package code	98ASA01448D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	-	4	-	mm
package width	-	4	-	mm
seated height	-	1.37	-	mm
nominal pitch	-	0.8	-	mm
actual quantity of termination	-	16	-	



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2 Package outline

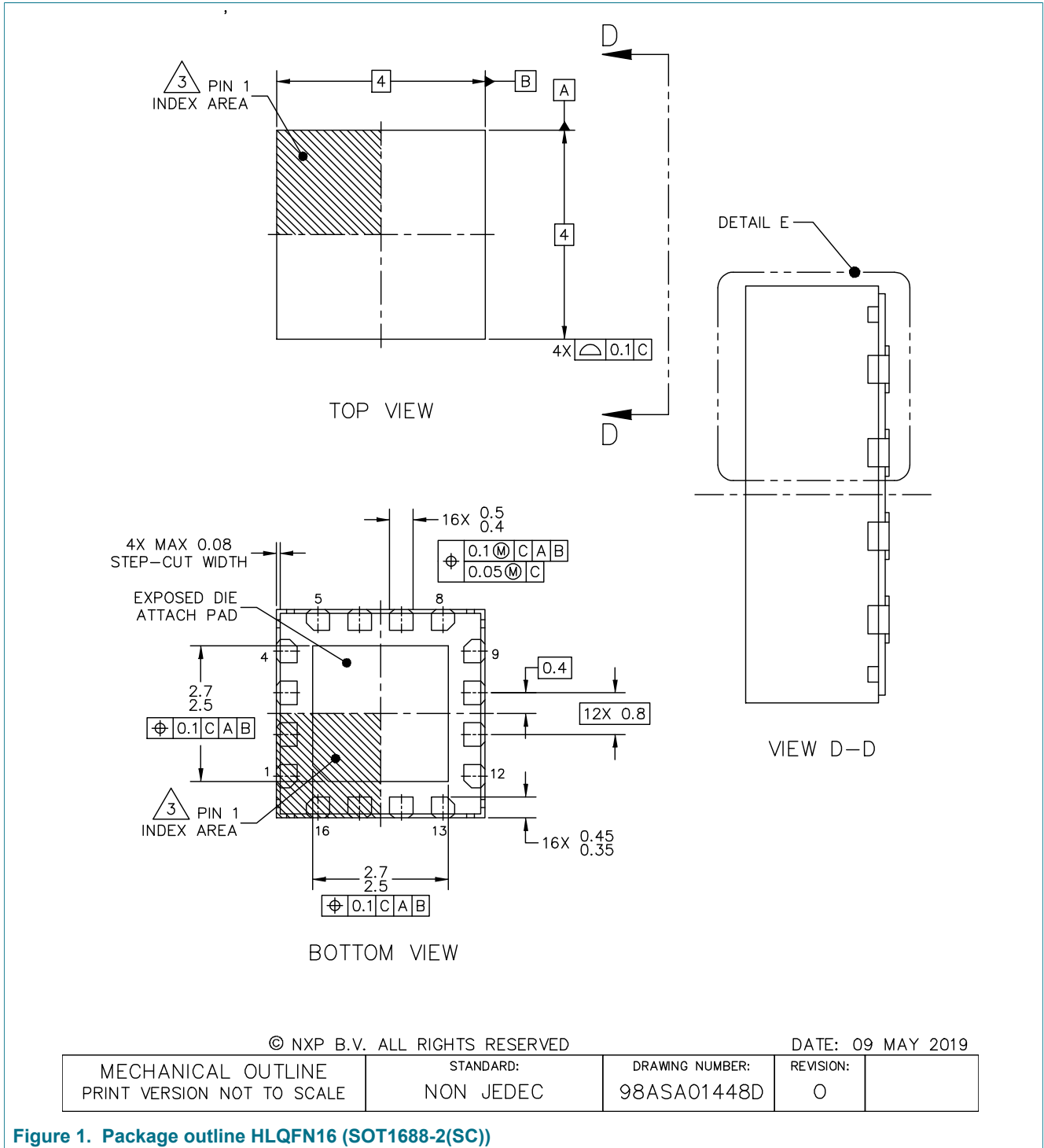
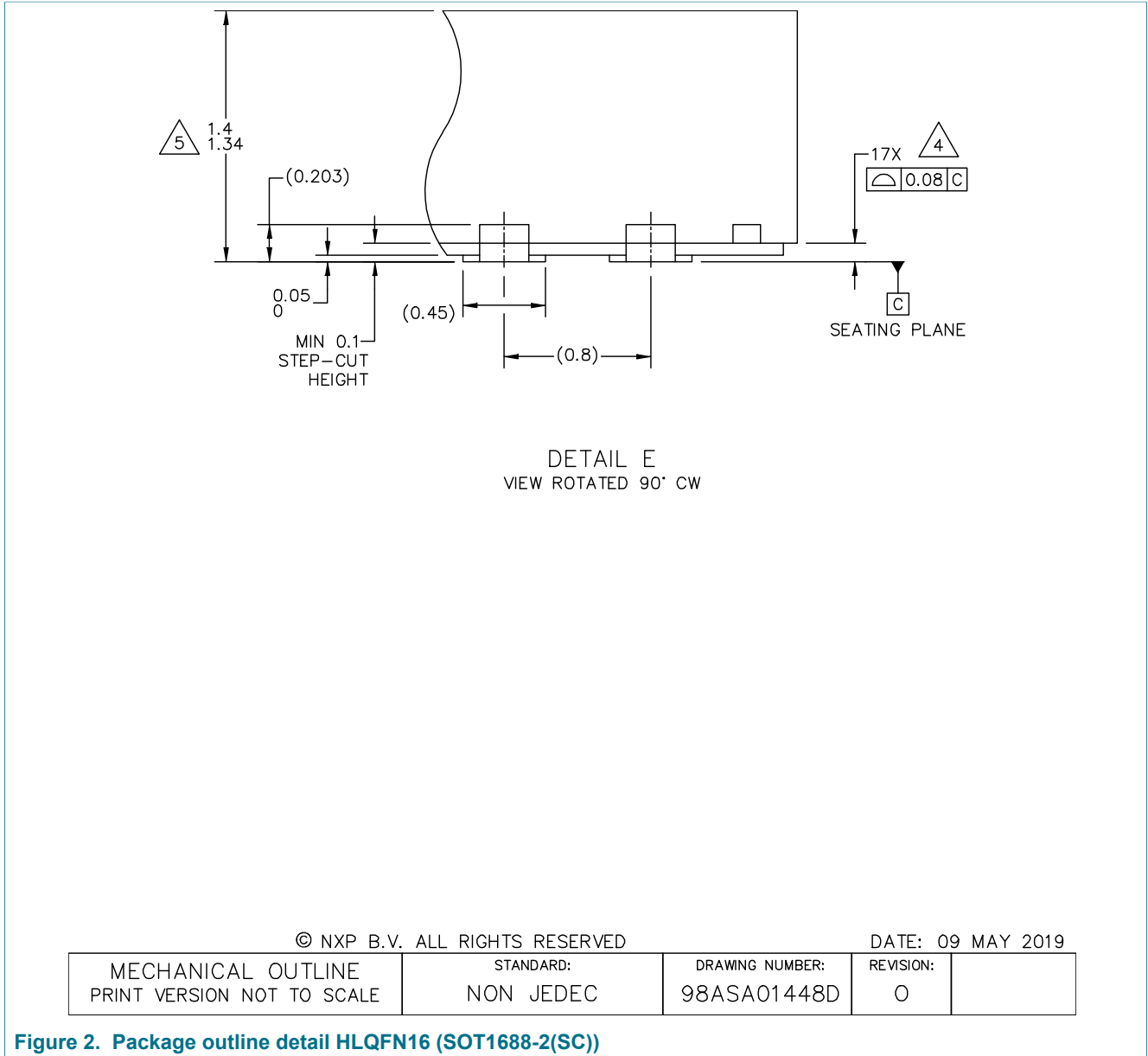


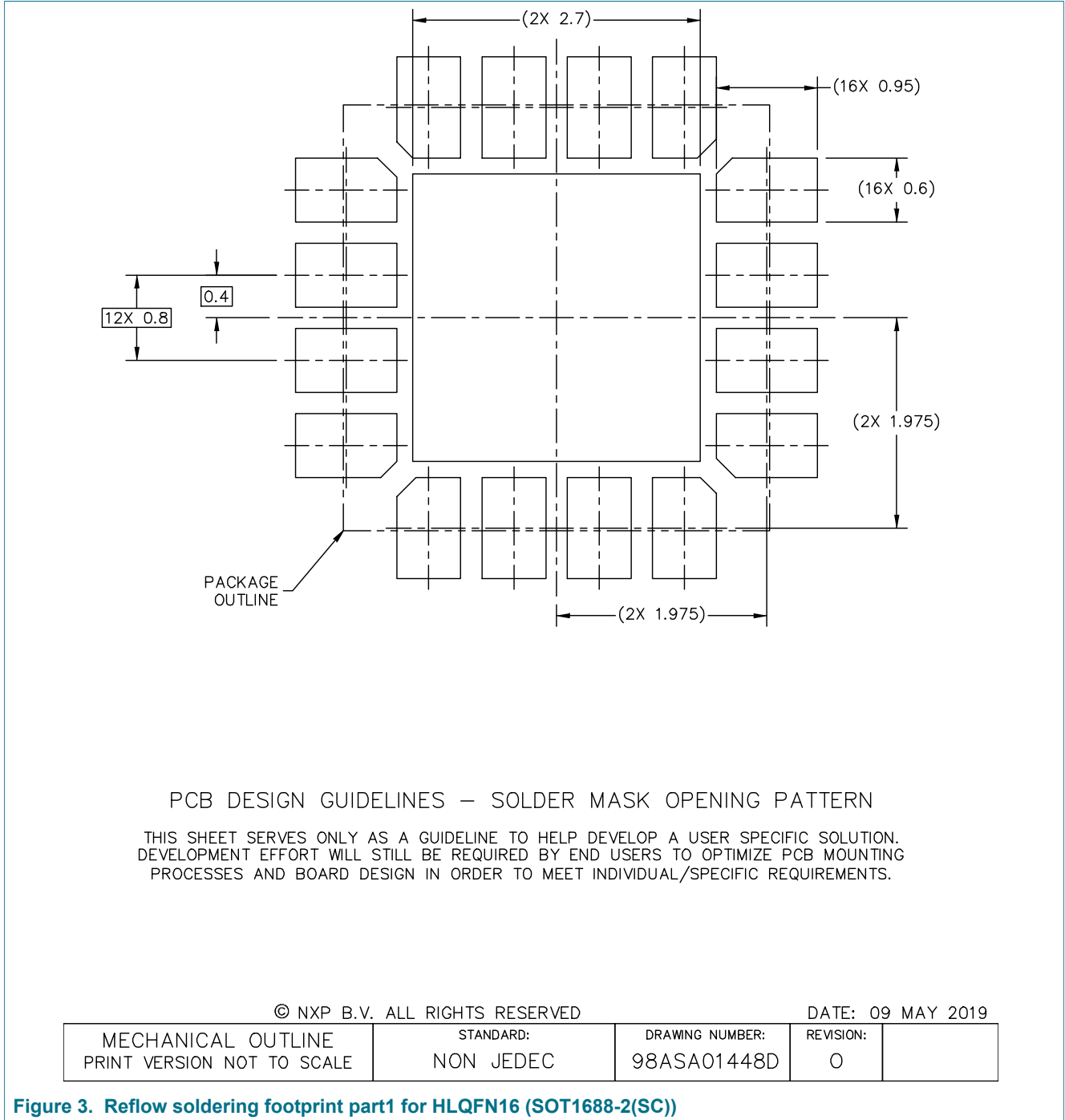
Figure 1. Package outline HLQFN16 (SOT1688-2(SC))

HLQFN16; plastic, thermal enhanced low profile quad flat non-leded package; 16 terminals; 0.8 mm pitch; 4 mm x 4 mm x 1.37 mm body

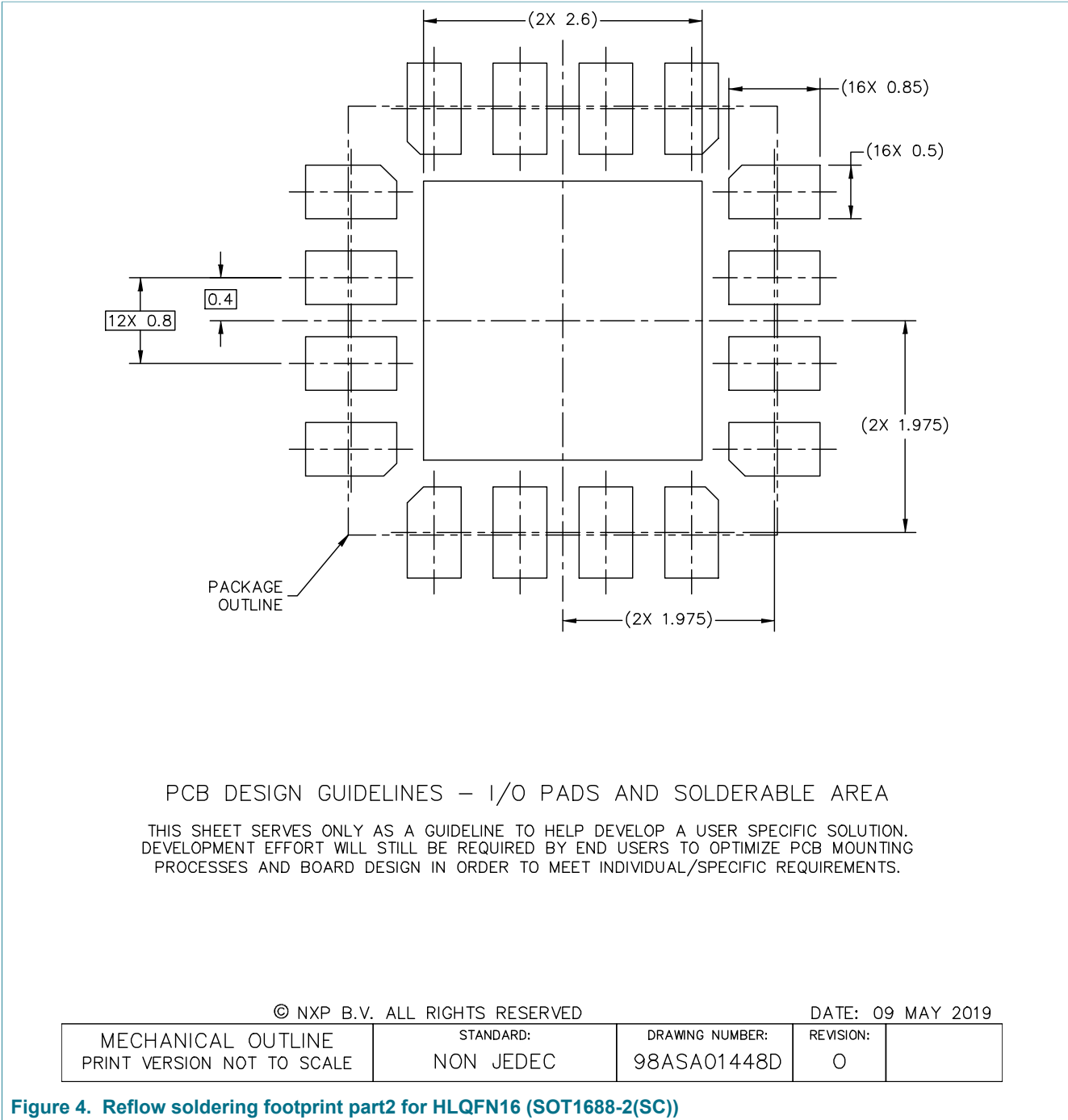


HLQFN16; plastic, thermal enhanced low profile quad flat non-leded package; 16 terminals; 0.8 mm pitch; 4 mm x 4 mm x 1.37 mm body

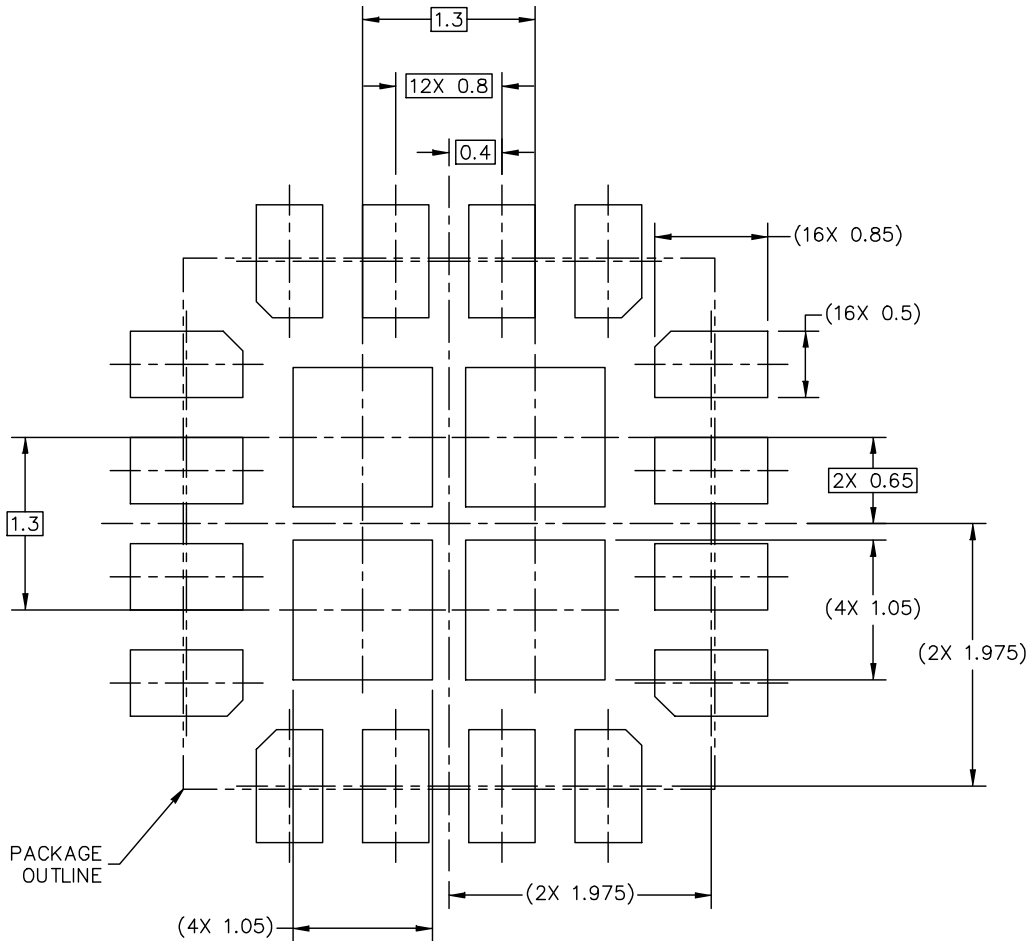
3 Soldering



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RECOMMENDED STENCIL THICKNESS 0.125 OR 0.15

PCB DESIGN GUIDELINES – SOLDER PASTE STENCIL

THIS SHEET SERVES ONLY AS A GUIDELINE TO HELP DEVELOP A USER SPECIFIC SOLUTION. DEVELOPMENT EFFORT WILL STILL BE REQUIRED BY END USERS TO OPTIMIZE PCB MOUNTING PROCESSES AND BOARD DESIGN IN ORDER TO MEET INDIVIDUAL/SPECIFIC REQUIREMENTS.

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MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: 98ASA01448D	REVISION: O	
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Figure 5. Reflow soldering footprint part3 for HLQFN16 (SOT1688-2(SC))

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NOTES:

- 1. ALL DIMENSIONS ARE IN MILLIMETERS.
- 2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
- 3. PIN 1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.
- 4. COPLANARITY APPLIES TO LEADS AND DIE ATTACH FLAG.
- 5. SPUTTER LAYER IS INCLUDED IN THE TOTAL THICKNESS.

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Figure 6. Package outline note HLQFN16 (SOT1688-2(SC))

4 Legal information

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